

ABSTRACT

ELECTROLESS PALLADIUM PLATING SOLUTION

[Object] To provide an electroless palladium plating solution capable of forming a pure palladium plating film directly on an electroless nickel plating film without (pre-)treatment such as substituted palladium plating treatment or the like, which pure palladium plating film has good adhesion and small variations in plating film thickness.

[Means to Solve the Problem] An electroless palladium plating solution comprising: a first complexing agent, a second complexing agent, phosphoric acid or a phosphate, sulfuric acid or a sulfate, and formic acid or a formate; the first complexing agent being an organopalladium complex having ethylenediamine as a ligand ; the second complexing agent being a chelating agent having a carboxyl group or a salt thereof and/or a water-soluble aliphatic organic acid or a salt thereof.

Selected Figure : None